

PRODUCT NUMBER

57102-XXX-XXXXXL

PLATING

S = 0.38µm GOLD/GXT ON CONTACT AREA
2µm MIN MATTE TIN ON TAIL

G = 0.76µm GOLD/GXT ON CONTACT AREA
2µm MIN MATTE TIN ON TAIL

F = GOLD FLASH ON CONTACT AREA
2µm MIN MATTE TIN ON TAIL

1.27µm MIN NICKEL UNDERPLATING

RoHS COMPATIBLE SEE NOTE 7

POLARIZATION, SEE NOTE 6

PACKAGING, SEE NOTE 5

NB OF POSITIONS PER ROW: 02 TO 25 POS

PIN STYLE	POST LENGTH	TAIL LENGTH	OAL
02	2.00	2.50	6.00
04	2.00	3.00	6.50
06	4.00	2.50	8.00
08	4.00	3.00	8.50
10	6.00	3.00	10.50
12	5.71	4.37	11.58

NOTES:

1. MATERIAL HOUSING: HIGH TEMP. THERMOPLASTIC
UL 94V-0, COLOR BLACK

2. MATERIAL TERMINAL: COPPER ALLOY

3. TO DETERMINE DIMENSIONS:
N = NUMBER OF POSITIONS PER ROW

4. 7N MIN. PIN RETENTION IN EITHER DIRECTION.

5. PACKAGING:

= STANDARD PACKAGING IN POLYBAGS

- = PACKAGING POLYBAGS WHEN POLARIZATION FEATURE APPLICABLE

U = TUBE AVAILABLE FROM 03 TO 25 POS PER ROW

6. FOR POLARIZATION, SPECIFIED PIN

EXAMPLE : 03 = OMIT PIN POSITION 3, SEE TOP VIEW

OMIT FROM PRODUCT NUMBER IF THIS FEATURE IS NOT APPLICABLE

7. RoHS COMPATIBLE PRODUCT SPECIFICATIONS

a - PLATING:

- "LF" MEANS THE PRODUCT IS LEAD-FREE,
2µm MINIMUM MATTE TIN OVER 1.27µm
MINIMUM NICKEL UNDERPLATE.

b - MANUFACTURING PROCESS COMPATIBILITY

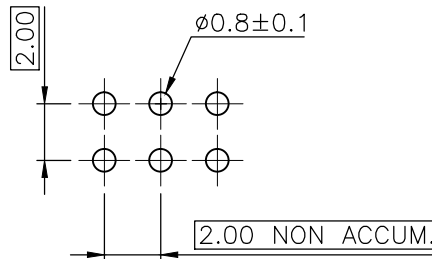
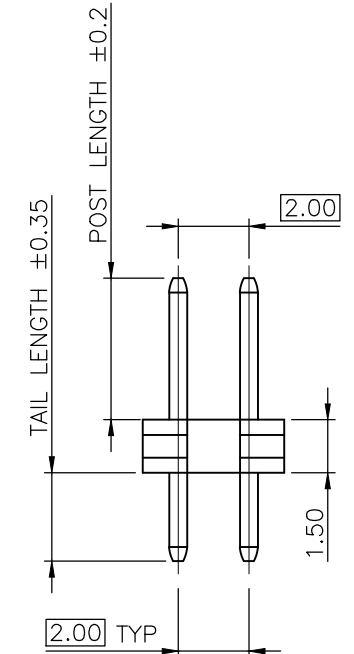
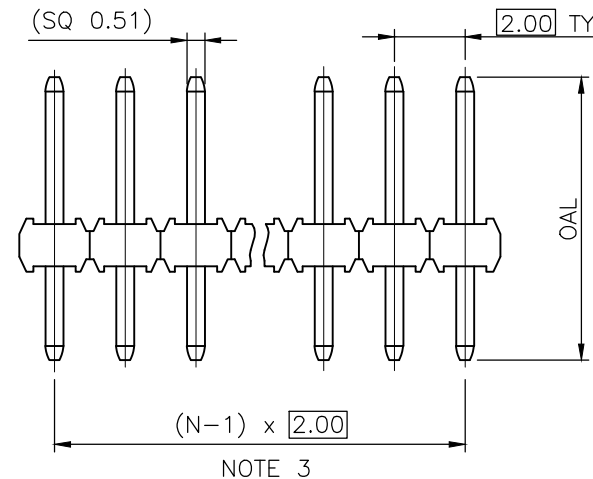
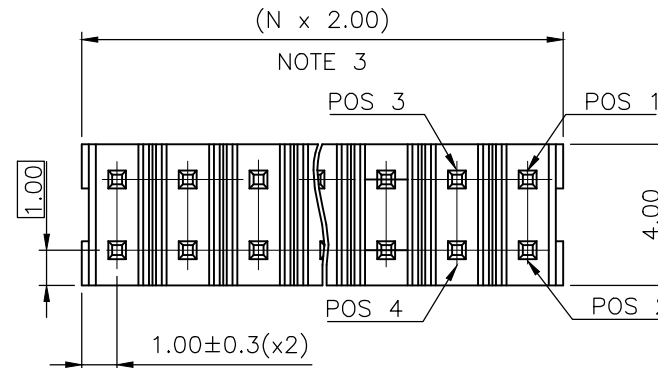
- THE HOUSING WILL WITHSTAND EXPOSURE TO
260°C ±5°C SOLDER BATH TEMPERATURE FOR
5 SECONDS IN A WAVE SOLDER APPLICATION
WITH A 1.6mm MIN THICK CIRCUIT BOARD.
- COMPATIBLE TO REFLOW PROCESS 260°C MAX
FOR 30 SECONDS

c - LABELLING:

- MEETS PACKAGING SPECS AS PER GS-14-920

d - LEGAL STATEMENT : SEE GS-47-0004

TOP VIEW



RECOMMENDED HOLE PATTERN

mat'l. code				surface ISO 1302 ✓		tolerance ISO 406 ISO		projection 101 		product family MINITEK									
ltr		ecn no		dr		date		tolerances unless otherwise specified				title							
L		F12-0062		LMU		12.05.25		angles		linear		.X ±0.3		 mm		UNSH HEADER 2.00 mm VERTICAL TMT			
M		B-19190		LMU		14.10.24						.XX ±0.13							
N		B-19797		AMA		14.12.16						.XXX ±0.05							
P		B-19988		LMU		15.01.13		dr		L.MULIN		04.05.06				dwg no 57102		sheet 1 of 1 A3	
J		F08-0145		ELA		17.04.08		engr		J.COMPAGNON		04.11.25							
K		F11-0026		JCO		11.05.12		appd		JM.C		04.11.25							
sheet index		revision sheet																	
								</											